

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A semiconductor package comprising:
 - a chip carrier including a grounded pad on a first side of said chip carrier;
 - a semiconductor chip coupled to said first side of said chip carrier;
 - a conductive lid thermally coupled to said semiconductor chip, wherein the entire length of said conductive lid is substantially parallel with said first side of said chip carrier;
 - and
 - a discrete conductive structure having about the same dimensions as a discrete chip component, wherein said discrete conductive structure is electrically coupled to said grounded pad and to said conductive lid.
2. (Original) The semiconductor package of claim 1 wherein a solder connects said conductive structure and said grounded pad.
3. (Original) The semiconductor package according to claim 1 wherein said conductive structure is electrically coupled to said grounded pad with an electrically conductive adhesive material.
4. (Original) The semiconductor package according to claim 1 wherein said conductive structure is electrically coupled to said conductive lid with an electrically conductive adhesive material.
5. (Original) The semiconductor package according to claim 1 wherein said conductive structure is coupled to said chip carrier using an electrically insulative adhesive material.
6. (Original) The semiconductor package according to claim 1 wherein said conductive structure is coupled to said chip carrier using a thermally conductive adhesive material.
7. (Original) The semiconductor package according to claim 1 wherein said conductive

structure comprises a spring.

8. (Original) The semiconductor package according to claim 1 wherein said conductive structure comprises a block.
9. (Previously Presented) The semiconductor package according to claim 1 wherein said conductive structure comprises a surface mount technology (SMT) discrete component.
10. (Previously Presented) The semiconductor package according to claim 1 wherein a solder couples said conductive structure to said grounded pad;
an electrically conductive adhesive material couples said conductive structure to said conductive lid; and
an electrically insulative adhesive material couples said conductive structure to said chip carrier.
11. (Original) The semiconductor package according to claim 10 wherein said conductive structure comprises a conductive spring.
12. (Original) The semiconductor package according to claim 10 wherein said conductive structure comprises a block.
13. (Original) The semiconductor package according to claim 10 wherein said conductive structure comprises a surface mount technology (SMT) discrete component.

Claims 14 – 21 (Cancelled)

22. (Previously Presented) The semiconductor package of claim 1 wherein an end of said conductive lid extends beyond at least one side of said semiconductor chip.
23. (Previously Presented) The semiconductor package of claim 1 wherein said conductive

structure is located on said first side of said chip carrier.

24. (New) The semiconductor package of claim 1 wherein said conductive structure has about the same dimensions as a surface mount technology (SMT) discrete component.
25. (New) The semiconductor package of claim 1 wherein said conductive structure occupies a substantial amount of a gap between a lower surface of said conductive lid and an upper surface of said chip carrier.
26. (New) The semiconductor package of claim 25 wherein said conductive structure occupies about 90% of said gap.